2-PARTSILICONEGAP FILLER TDG-Z8-SI-2C HALA

dispensable / 2 parts / Form-in-Place

TDG-Z8-SI-2C is a 2-part dispensable silicone gap filler which is filled with thermally conductive fillers. After curing under heat the system remains elastic. It is characterised by very good dielectric and mechanic properties and is suited for compensating extreme tolerances and spaces at non-coplanar systems. Its thixotropic behaviour allows for a definite placement and cure-in-place. It has a natural low level tack that enhances a good thermal contact.



Technical Data Sheet Release 07 / 2025

PROPERTIES

- 🗆 Dispensable 2-part silicone
- Thermal conductivity: 8.0 W/mK
- Remains elastic after polymerisation
- Zero stress on components
- Heat accelerated curing
- Shock absorbing

AVAILABILITY

 Cartridges 2 x 25 ml / 2 x 200 ml / 2 x 600 ml
Pail 2 x 25 kg

APPLICATION EXAMPLES

- Thermal link of: FPBGA
- Capacitors
- Heat Pipes
- BGA
- For use in Automotive applications / Telecommunication / Multimedia / Industrial PCs

PROPERTY	UNIT	A PART	B PART	
MATERIAL		Silicone	Silicone	
Colour		Blue	White	
Density በ 25 °C	g/cm³	3.25	3.25	
Mixing Ratio	Weight or Volume	1:1	1:1	
Hardness	Shore 00	65	65	
Viscosity	Pas	200	180	
Viscosity (mixed)	Pas	190	190	
Pot Life @ 25 °C and 65 % RH (Time for viscosity to double)	Minutes	40 – 90	40 - 90	
Curing Time @ 25 °C / 80 °C	Hours / Minutes	10 ±2 / 30 ±10	10 ±2 / 30 ±10	
Shelf Life (from Date of Manu- facturing, unopened, dry storage conditions @ -15 - 35 °C)	Months	9	9	
Flammability (Equivalent)	UL 94	VO	V0	
RoHS Conformity	2015 / 863 / EU	Yes	Yes	
TECHNICAL				
Thermal Conductivity'	W/mK	8	8	
Operating Temperature	°C	- 40 to + 150	- 40 to + 150	
Dielectric Strength	kV/mm	≥ 8	≥ 8	
Volume Resistivity	Ohm - cm	≥ 1 x 10 ¹²	≥ 1 x 10 ¹²	•••••

Measurement technique according to: 'ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information. Warning: Only A / B part of the same lot number may be processed together.

